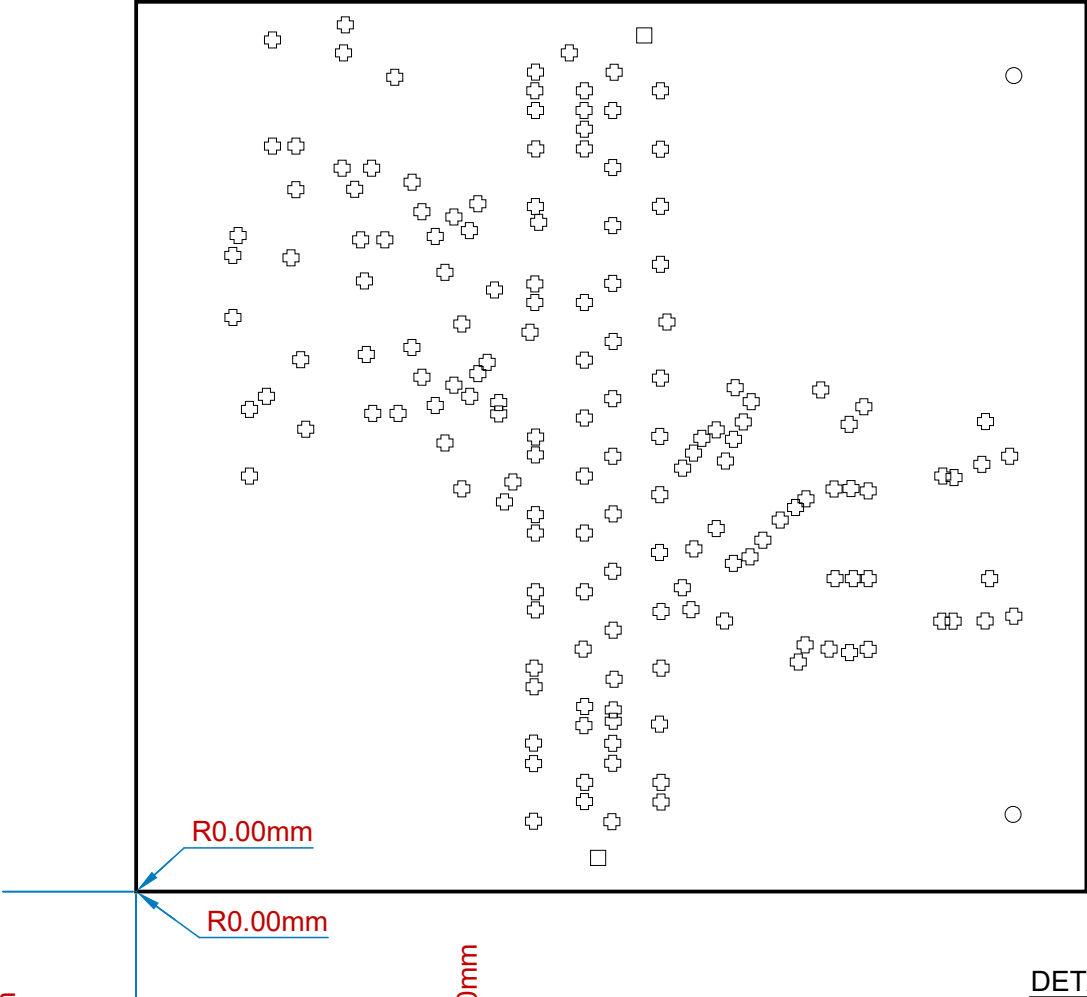


Manufacturing documentation:

Drill Drawing View (Scale 2:1)



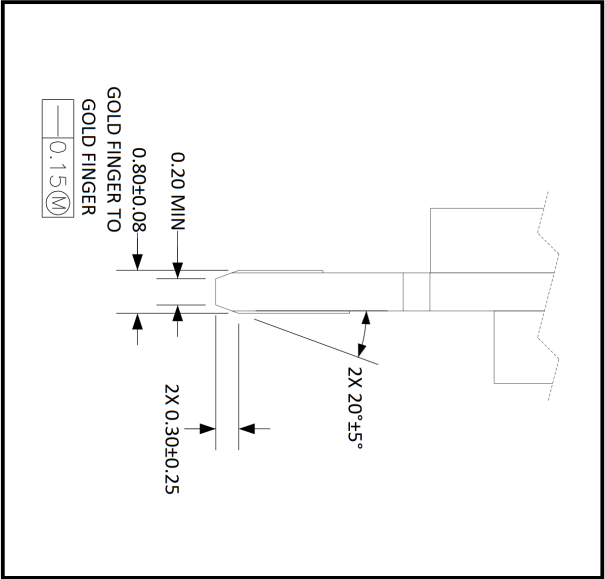
Board Layer Stack

Material	Layer	Thickness	Dielectric Material	Type	Gerber	Comments	Dk	Frequency
	Top Overlay			Legend	GTO			
Surface Material	Top Solder	0.03mm	SM-001	Solder Mask	GTS	black	4	1GHz
Nickel, Gold	Top Surface Finish	0.00mm		Surface Finish				
CF-004	Top Layer	0.04mm		Signal	GTL			
Prepreg		0.11mm	PP-017	Dielectric		-	4,29	1GHz
CF-004	GND	0.04mm		Internal Plane	GP1			
Core		1.20mm	Core-039	Dielctric		-	4,8	1GHz
CF-004	PWR	0.04mm		Internal Plane	GP2			
Prepreg		0.11mm	PP-017	Dielectric		-	4,29	1GHz
CF-004	Bottom Layer	0.04mm		Signal	GBL			
Nickel, Gold	Bottom Surface Finish	0.00mm		Surface Finish				
Surface Material	Bottom Solder	0.03mm	SM-001	Solder Mask	GBS	black	4	1GHz
	Bottom Overlay			Legend	GBO			
Total thickness: 1.62mm								

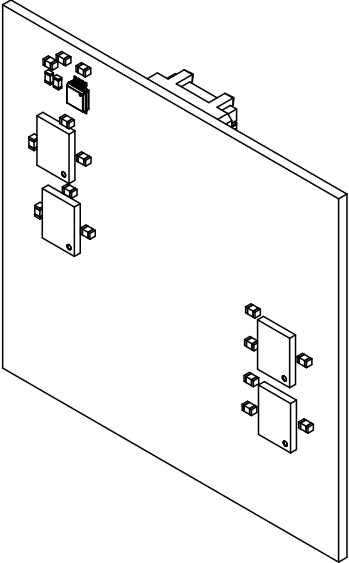
Drill Table

Symbol	Count	Hole Size	Plated	Hole Tolerance
⊕	158	0.30mm	Plated	
□	2	1.27mm	Non-Plated	
○	2	3.20mm	Plated	
162 Total				

DETAIL A



View from Top side (Scale 1:1)



Notes:

- 1. impedance matched stackup
- 2. 0.1mm trace width / clearance

Project:
uSD Card Module

Drawing number:
Date: 20/05/2024

Rev: PA

Format:
A3

Laboratory: IIS

Drawn by: MAYERPH

Sheet: FMC_4_Hyper_fabrication.PCBDwf

Page: 1 of 1

File: C:\Users\User\Desktop\fmc_peripheral_boards-master\05_FMC_4_Hyperram_32MB\FMC_4_Hyper_fabrication.PCBDwf